

FEATURES

Low profile package

I Idea for printed circuit board

Glass passivated Junction chip

High forward surge current capability

Low reverse leakage





Schematic Symbol

MECHANICAL DATA

Case Material: Molded Plastic. UL Flammability Classification	
Rating 94V-0	
Moisture Sensitivity: Level 1 per J-STD-020	
Polarity: Cathode line denotes the cathode end	

APPROVALS

	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

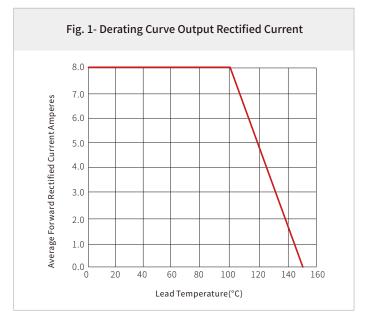
MAXIMUM RATINGS AND CHARACTERISTICS ($T_A = 25$ °C)

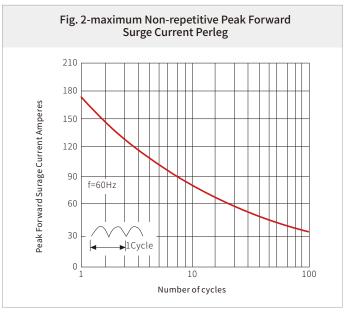
Parameter		Symbol	GS8AC	GS8BC	GS8DC	GS8GC	GS8JC	GS8KC	GS8MC	Unit
Marking			GS8AC	GS8BC	GS8DC	GS8GC	GS8JC	GS8KC	GS8MC	
Maximum Repetitive Peak Reverse Voltage		V _{RRM}	50	100	200	400	600	800	1000	
Maximum RMS Voltage		V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage		V _{DC}	50	100	200	400	600	800	1000	
Maximum Average Forward Rectified Current At T,=100°c		I _{F(AV)}	8.0							А
Surge Peak Forward Current,8.3ms Single Half Sine-Wave Superimposed On Rated Load Per Diode		I _{FSM}	175.0							
Maximum Instantaneous Forward Voltage at 8.0A		$V_{\rm F}$	1.0						V	
Maximum Reverse Current	T _J =25°C					2.0				Δ.
@Rated V _R	T _J =125°C	I _R	200						μΑ	
Typical Junction Capacitance (Note1)		CJ	60.0						рF	
Typical Thermal Resistance		$R_{\theta J-A}$	47.0						°C/W	
Operating Junction And Storage Temperature Range		$T_{J},\!T_{STG}$	-55 to +150					°C		

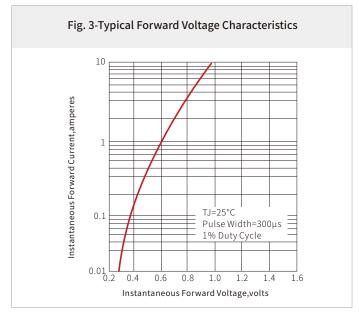
Note 1: Measured At 1mhz And Applied Reverse Voltage Of 4.0v D.C.

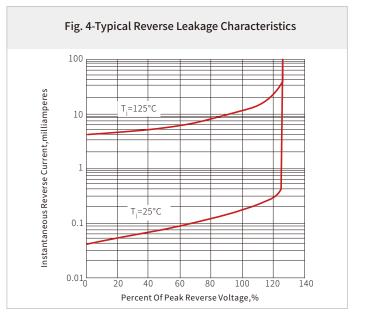


CHARACTERISTIC CURVES





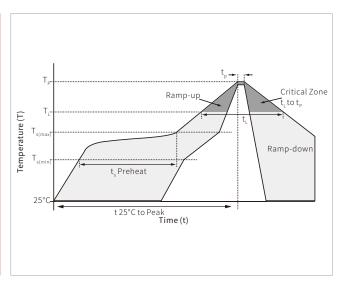




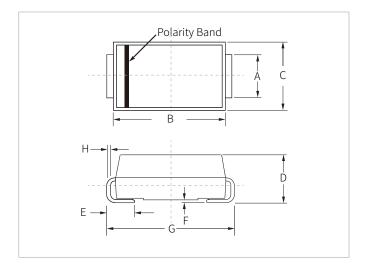


SOLDERING PARAMETERS

	Lead-free assembly	
	Temperature Max $(T_{s(min)})$	150°C
Pre Heat	Temperature Max $(T_{s(max)})$	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ran	np up rate (Liquidus Temp (T_L) to peak	3°C/second max
	3°C/second max	
Reflow	Temperature (T _L) (Liquidus)	217°C
Renow	Time (min to max) (t_L)	60 – 150 seconds
Peak Temp	260°C	
Time within	20 – 40 seconds	
Ramp-dow	6°C/second max	
Time 25°C t	8 minutes max.	
Do not exce	260°C	



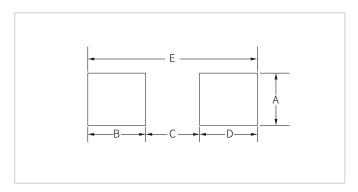
DO-214AB(SMC) PACKAGE INFORMATION



Ref.	Millim	neters	Inches		
i.c.i	Min.	Max.	Min.	Max.	
А	2.80	3.20	0.110	0.126	
В	6.60	7.20	0.260	0.283	
С	5.70	6.10	0.224	0.240	
D	2.15	2.75	0.085	0.108	
Е	1.00	1.60	0.039	0.063	
F	0.02	0.20	0.000	0.008	
G	7.60	8.00	0.299	0.315	
Н	0.15	0.30	0.006	0.012	



RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millim	neters	Inches		
ici.	Min.	Max.	Min.	Max.	
А	3.30	-	0.129	-	
В	2.40	-	0.094	-	
С	-	4.20	-	0.165	
D	2.40	-	0.094	-	
Е	8.20REF		0.32	3REF	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
GS8AC-GS8MC	DO-214AB(SMC)	3000PCS	13"



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